DESCRIPTION

The SPN3406 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

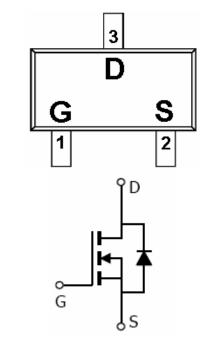
APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

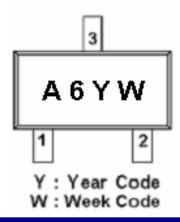
FEATURES

- 30V/5.4A, RDS(ON)= 40Ω @VGS=10V
- 30V/4.6A, RDS(ON)= 50Ω @, VGS=4.5V
- ◆ Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ SOT-23-3L package design

PIN CONFIGURATION(SOT-23-3L)



PART MARKING



PIN DESCRIPTION					
Pin	Symbol	Description			
1	G	Gate			
2	S	Source			
3	D	Drain			

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN3406S23RG	SOT-23-3L	A6YW

Week Code : A ~ Z(1 ~ 26); a ~ z(27 ~ 52)
 SPN3406S23RG : Tape Reel; Pb – Free

ABSOULTE MAXIMUM RATINGS

(Ta=25°C Unless otherwise noted)

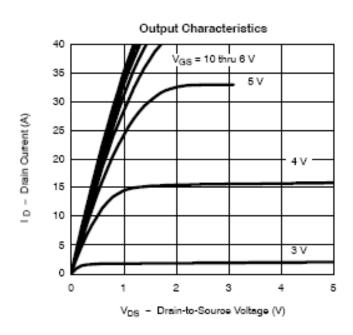
Parameter		Symbol	Typical	Unit	
Drain-Source Voltage		Vdss	30	V	
Gate –Source Voltage		VGSS	±20	V	
Continuous Durin Comment/Tr-150°C)	TA=25°C	In	4.0	Δ.	
Continuous Drain Current(T」=150°C)	Ta=70°C	- Id	3.2	A	
Pulsed Drain Current	Ірм	25	A		
Continuous Source Current(Diode Conduction)		Is	1.7	A	
Decree Dissipation	TA=25°C	D-	2.0	W	
Power Dissipation	Ta=70°C	PD	1.3	W	
Operating Junction Temperature		Тл	150	$^{\circ}\!\mathbb{C}$	
Storage Temperature Range		Tstg	-55/150	$^{\circ}\mathbb{C}$	
Thermal Resistance-Junction to Ambient		RθJA	90	°C/W	

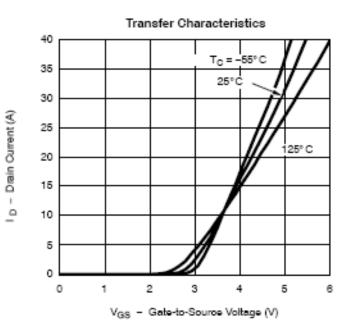
ELECTRICAL CHARACTERISTICS

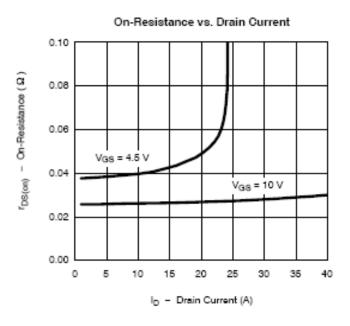
(Ta=25°C Unless otherwise noted)

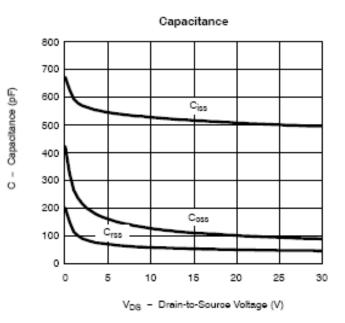
Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V(BR)DSS	V _G S=0V,I _D =250uA	30			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250uA	1.0		3.0] '	
Gate Leakage Current	Igss	V _{DS} =0V,V _{GS} =±20V			±100	nA	
		V _{DS} =24V,V _{GS} =1.0V			1		
Zero Gate Voltage Drain Current	Idss	$V_{DS}=24V, V_{GS}=0.0V$ $T_{J}=55^{\circ}C$			10	uA	
On-State Drain Current	ID(on)	$V_{DS} \ge 4.5V, V_{GS} = 4.5V$	10			A	
Drain-Source On-Resistance	RDS(on)	V _{GS} = 10V,I _D =4.0A V _{GS} =4.5V,I _D =3.6A		0.028 0.035	0.040 0.050	Ω	
Forward Transconductance	gfs	VDS=4.5V,ID=5.4A		12		S	
Diode Forward Voltage	Vsd	Is=1.7A,VGS=0V		0.8	1.2	V	
Dynamic							
Total Gate Charge	Qg			10	18	nC	
Gate-Source Charge	Qgs	V _{DS} =15V _{GS} =10V I _D =6.7A		1.6			
Gate-Drain Charge	Qgd	10-0.71		3.2			
Input Capacitance	Ciss			450		pF	
Output Capacitance	Coss	V _{DS} =15V _{GS} =0V f=1MHz		240			
Reverse Transfer Capacitance	Crss			38			
Turn-On Time	td(on)			7	15	ns	
	tr	V _{DD} =15RL=15		10	20		
т. ОМТ	td(off)	-ID=1.0A,VGEN=10 RG=6Ω		20	40		
Turn-Off Time	tf	1		11	20		

TYPICAL CHARACTERISTICS

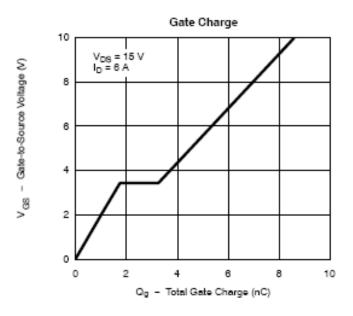


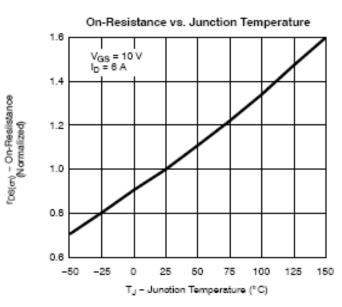


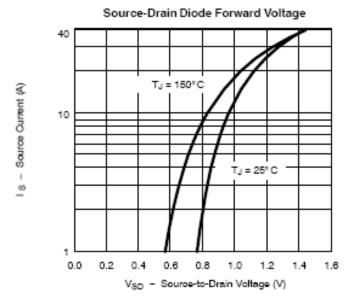


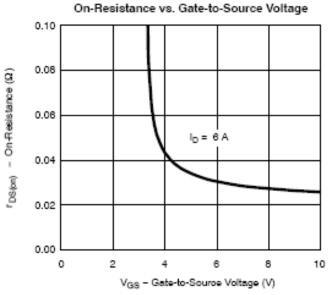


TYPICAL CHARACTERISTICS

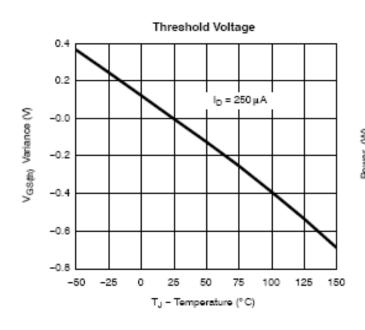


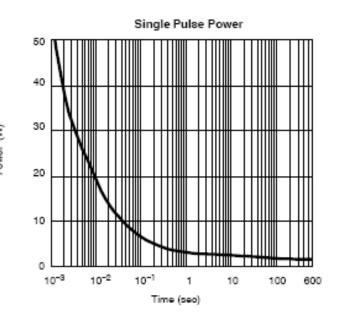




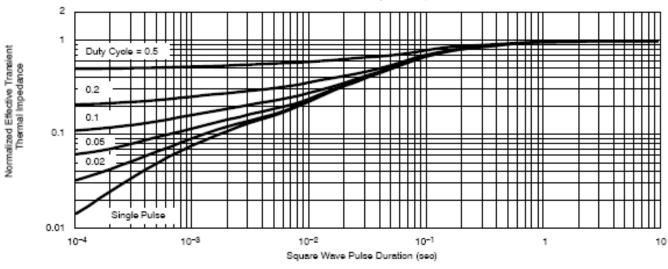


TYPICAL CHARACTERISTICS



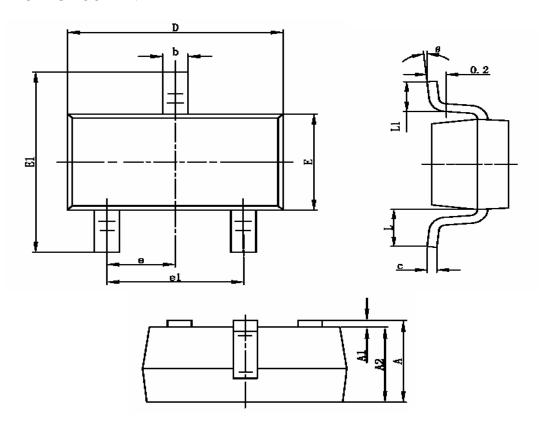


Normalized Thermal Transient Impedance, Junction-to-Foot





SOT-23-3L PACKAGE OUTLINE



Sumb al	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.400	0.012	0.016	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950TYP		0.03	7TYP	
e1	1.800	2.000	0.071	0.079	
L	0.700REF		0.028REF		
L1	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

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SYNC Power Corporation
9F-5, No.3-2, Park Street
NanKang District (NKSP), Taipei, Taiwan, 115, R.O.C
Phone: 886-2-2655-8178

Fax: 886-2-2655-8468 ©http://www.syncpower.com